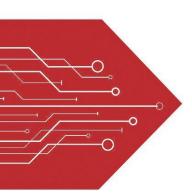
MSKSEMI















ESD

TVS

TSS

MOV

GDT

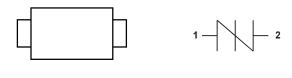
PLED

Broduct data speet



SURGE RATINGS

PART NUMBER	VPP 10x700u s (V)	
P0080FA-MS	3KV	



SOD-123FL

PART NUMBER AND ELEC TRICAL PARAMETER @ T=25°C RH = 45%-75%

TYPE	VDRM(V)	IDRM(uA)	Vs (v)	Is(ma)	Vr (v)	It(a)	Ih(ma)	CJ
P0080FA-MS	6	5	25	800	4	2.2	40	50

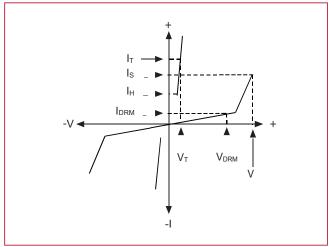
- **X** Vs is measured at 100KV/S
- imes Off-state capacitance is measured in VDC=2V, VRMS=1V,F=1MHz

THERMAL CONSIDERATIONS

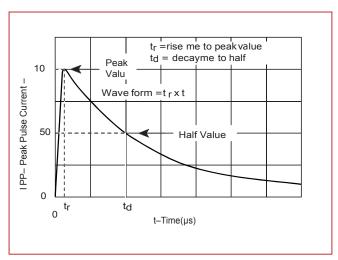
Symbol	Parameter	Value	Unit
T _J	Operaing Junc on Temperature	-55 to +1 25	°C
T _S	Storage Temperature Range	-55 to +150	C
R _{θЈ А}	Juncton to Ambient on printed circuit	120	℃/W



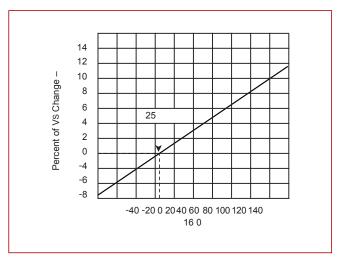
TYPICAL DEVICE CHARACTERISTICS



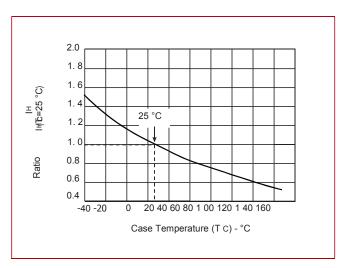
V-I Characteristics



tr x td Pulse Waveform



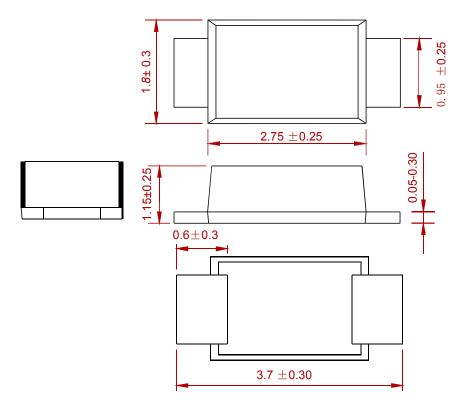
Normalized V_s Change vs. Junction Temperature



Normalized DC Holding Current vs. Case Temperature

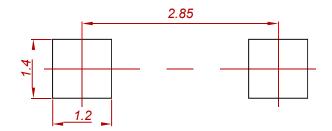


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
P0080FA-MS	SOD-123FL	3000



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